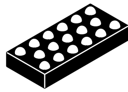
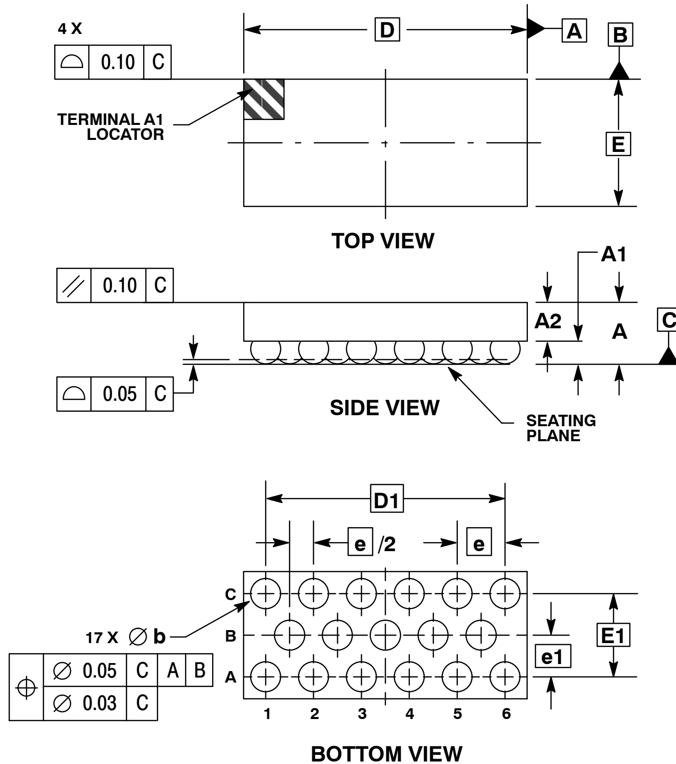


A1

SCALE 4:1

FLIP−CHIP−17 CSP
CASE 499AD−01
ISSUE A

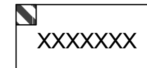
DATE 08 DEC 2005



NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETER.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

	MILLIMETERS	
DIM	MIN	MAX
A	−−−	0.740
A1	0.250	0.310
A2	0.380	0.430
D	2.960 BSC	
E	1.330 BSC	
b	0.350	0.410
e	0.500 BSC	
e1	0.435 BSC	
D1	2.500 BSC	
E1	0.870 BSC	

GENERIC
MARKING DIAGRAM*



XXXXXXXX = Specific Device Code

*This information is generic. Please refer to device data sheet for actual part marking.

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DESCRIPTION:	FLIP−CHIP−17 CSP, 2.96x1.3 MM, 350 μm SPHERE	PAGE 1 OF 1

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